



US00D717461S

(12) **United States Design Patent**  
**Oonuma et al.**

(10) **Patent No.:** **US D717,461 S**

(45) **Date of Patent:** **\*\* Nov. 11, 2014**

(54) **ADD-ON SAMPLE BUFFER MODULE**

(71) Applicant: **Hitachi High-Technologies Corporation**, Tokyo (JP)

(72) Inventors: **Mitsuru Oonuma**, Tokyo (JP); **Yoko Sato**, Fuchu (JP); **Naoto Tsujimura**, Hitachinaka (JP); **Kazuma Tamura**, Hitachinaka (JP)

(73) Assignee: **Hitachi High-Technologies Corporation**, Tokyo (JP)

(\*\*) Term: **14 Years**

(21) Appl. No.: **29/467,208**

(22) Filed: **Sep. 17, 2013**

(30) **Foreign Application Priority Data**

Mar. 21, 2013 (JP) ..... 2013-006211

(51) **LOC (10) Cl.** ..... **24-01**

(52) **U.S. Cl.**  
USPC ..... **D24/216**

(58) **Field of Classification Search**  
USPC ..... D24/216, 217, 219, 223, 231, 232, 233,  
D24/107, 169, 186; D10/81; 422/500, 547,  
422/62-65, 67; 435/287.1, 287.3; 436/43,  
436/45, 47

See application file for complete search history.

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

D653,766 S \* 2/2012 Oonuma et al. .... D24/216  
D655,422 S \* 3/2012 Oonuma et al. .... D24/216  
D655,823 S \* 3/2012 Oonuma et al. .... D24/216  
2008/0019868 A1 \* 1/2008 Okumoto et al. .... 422/63

**FOREIGN PATENT DOCUMENTS**

JP D 1414663 S 5/2011

**OTHER PUBLICATIONS**

JP Office Action Appln. No. D 2013-006211 dated Oct. 1, 2013 in the counterpart application with partial English translation.

(Continued)

*Primary Examiner* — Anhdao Doan

(74) *Attorney, Agent, or Firm* — Antonelli, Terry, Stout & Kraus, LLP.

(57) **CLAIM**

We claim the ornamental design for an add-on sample buffer module, as shown and described.

**DESCRIPTION**

FIG. 1 is a front, top and right side perspective view of a first embodiment of an add-on sample buffer module showing our new design;

FIG. 2 is a front elevational view thereof;

FIG. 3 is a rear elevational view thereof;

FIG. 4 is a left side elevational view thereof;

FIG. 5 is a right side elevational view thereof;

FIG. 6 is a top plan view thereof;

FIG. 7 is a bottom plan view thereof; and,

FIG. 8 is a right side elevational view thereof shown in an opened position.

FIG. 9 is a front, top and right side perspective view of a second embodiment of an add-on sample buffer module showing our new design;

FIG. 10 is a front elevational view thereof;

FIG. 11 is a rear elevational view thereof;

FIG. 12 is a left side elevational view thereof;

FIG. 13 is a right side elevational view thereof;

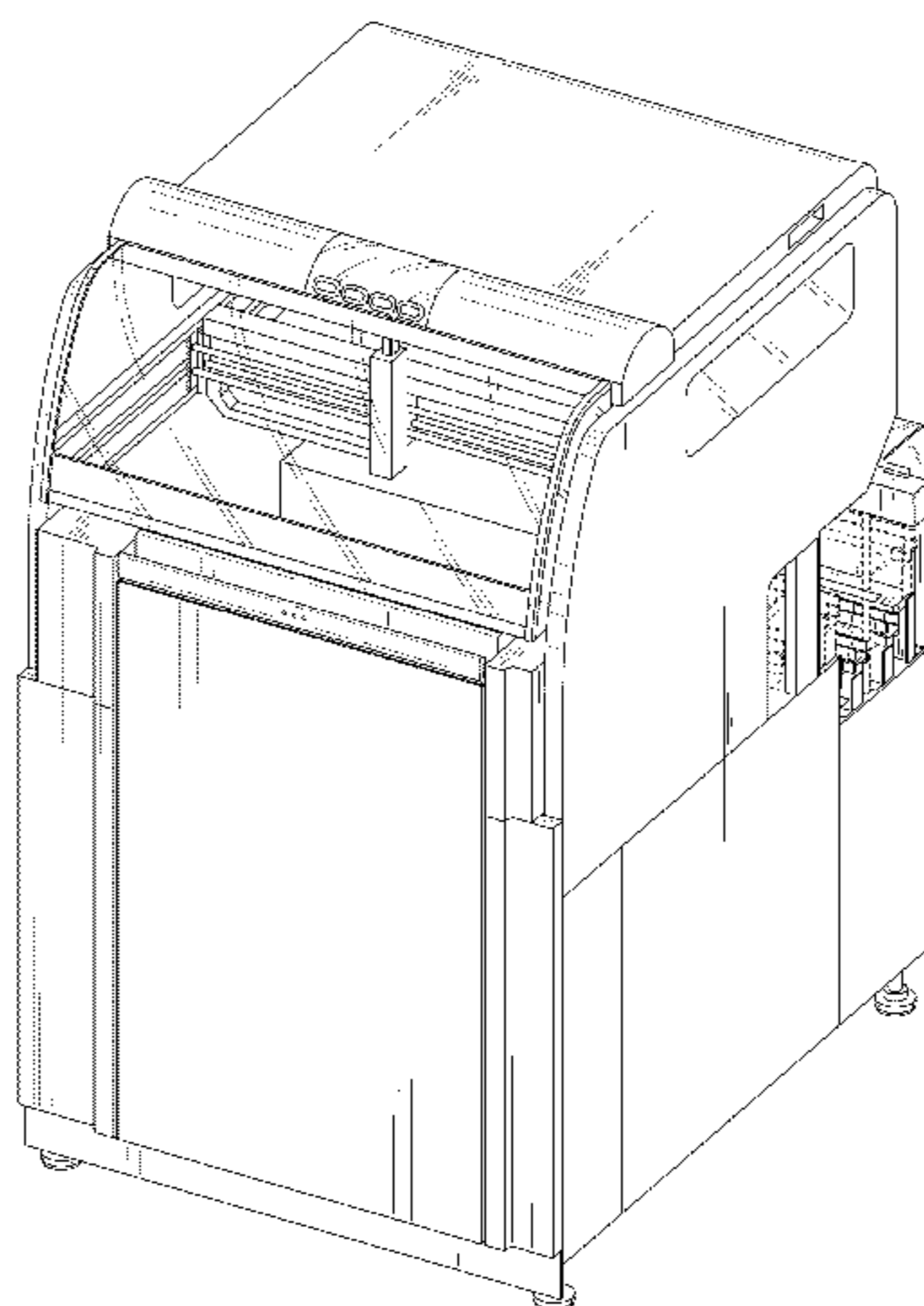
FIG. 14 is a top plan view thereof;

FIG. 15 is a bottom plan view thereof; and,

FIG. 16 is a right side elevational view thereof shown in an opened position.

The broken lines shown are for illustrative purpose and form no part of the claimed design.

**1 Claim, 16 Drawing Sheets**



(56)

**References Cited**

Exhibitor Name: Hitachi High-Technologies Corporation with partial English translation.

OTHER PUBLICATIONS

Prototype correspondent to the design of JP D 1470282 S; Prototype Exhibition Date: Oct. 11, 2012; Prototype Exhibited Country: Japan;

\* cited by examiner

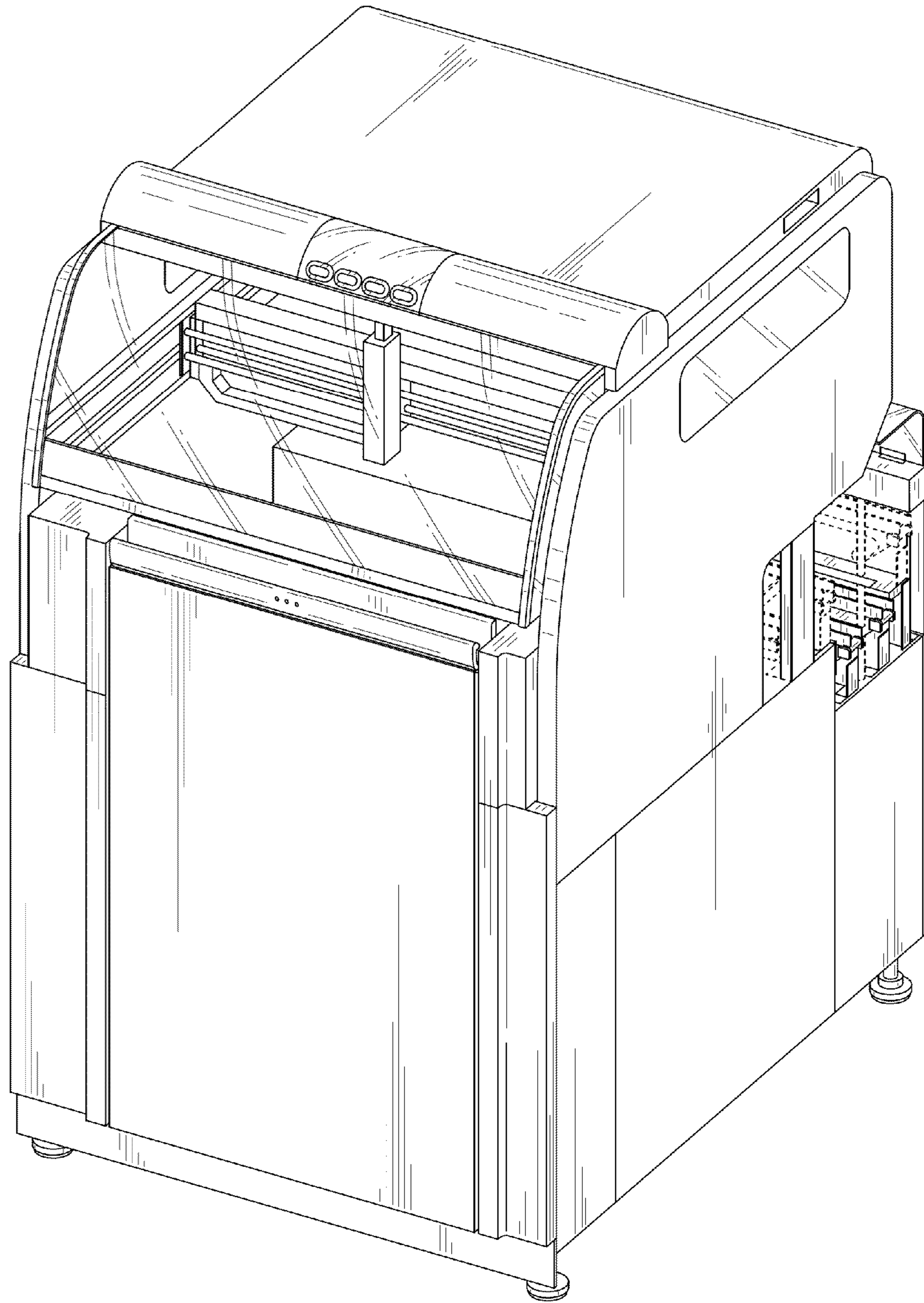


FIG. 1

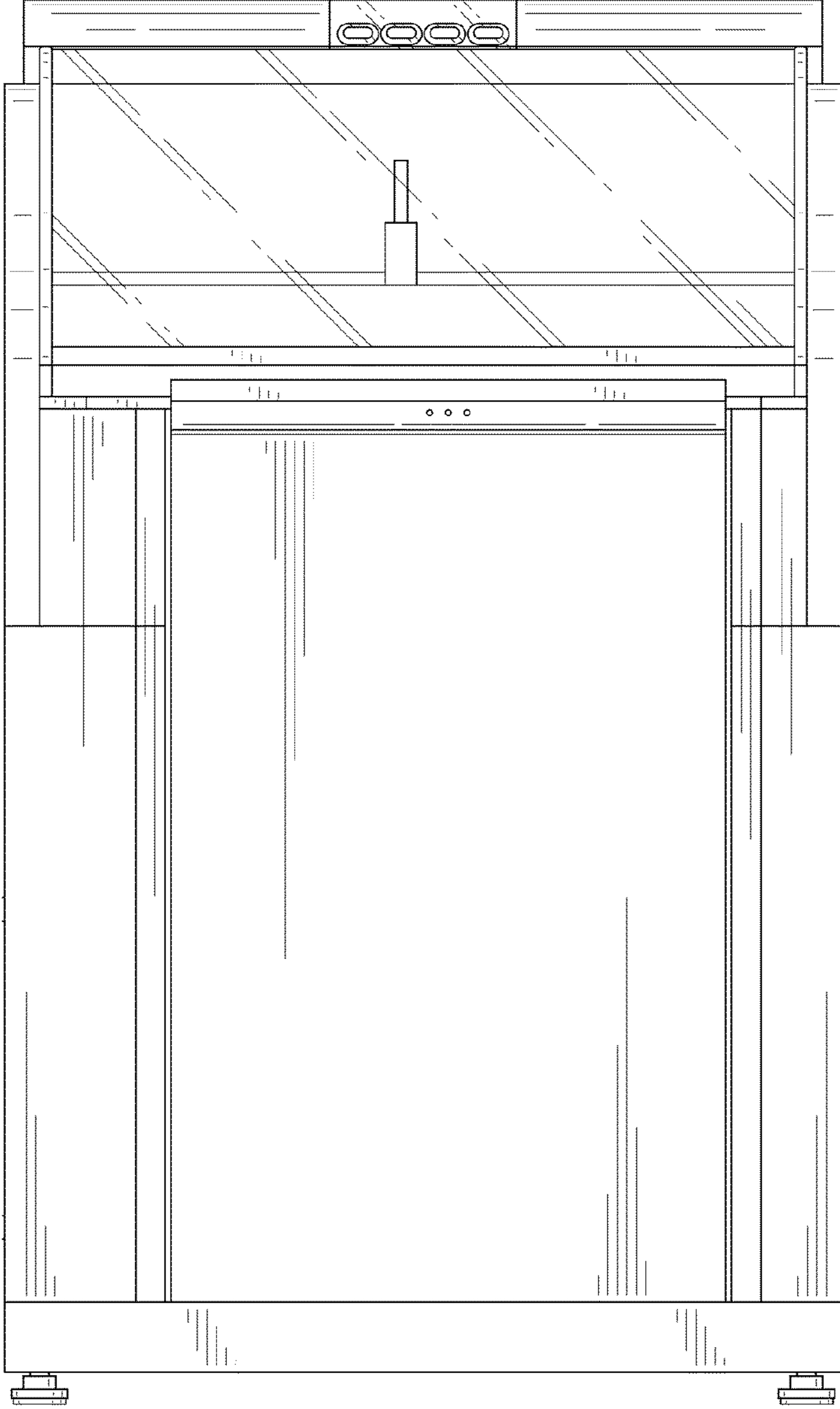


FIG. 2



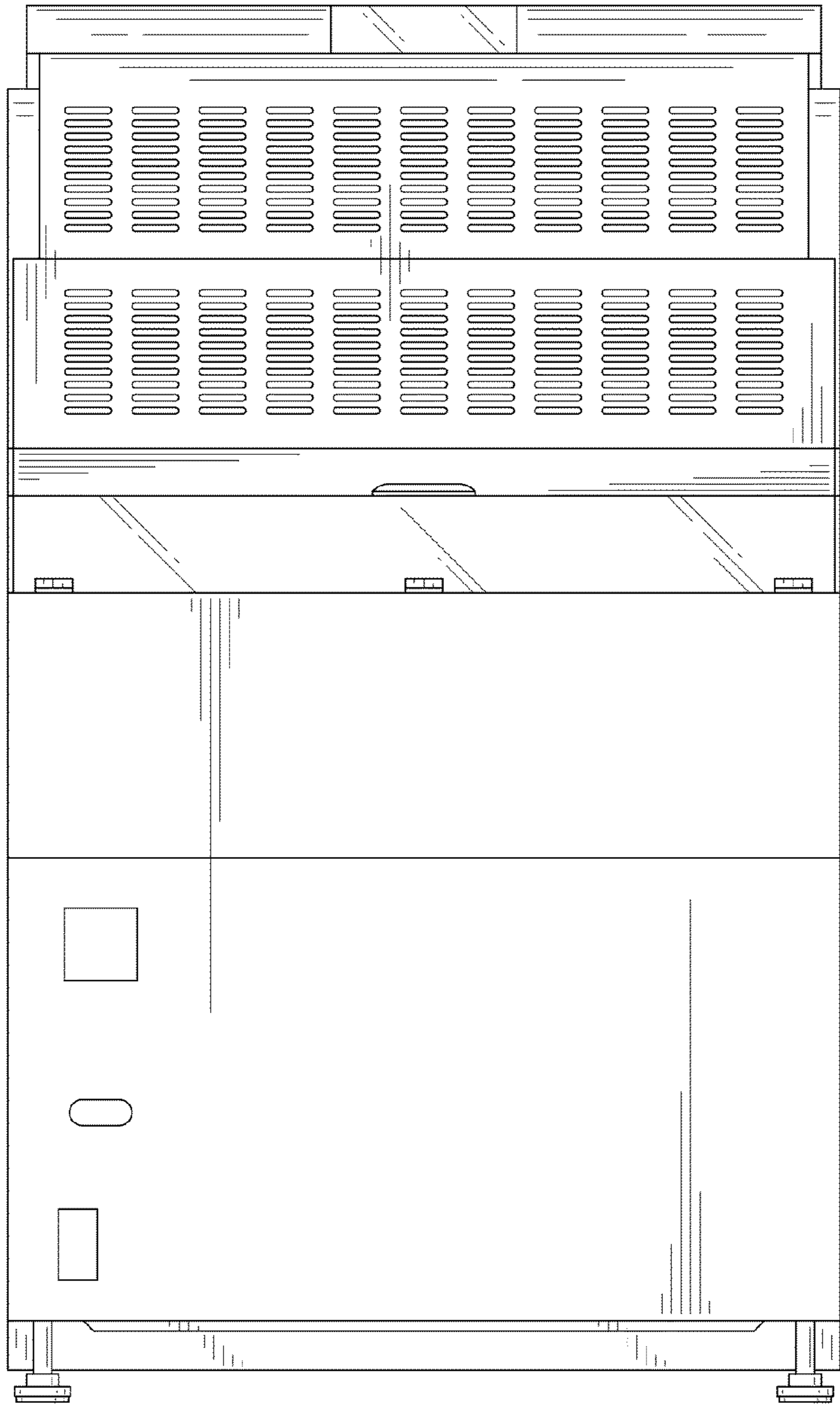


FIG. 3

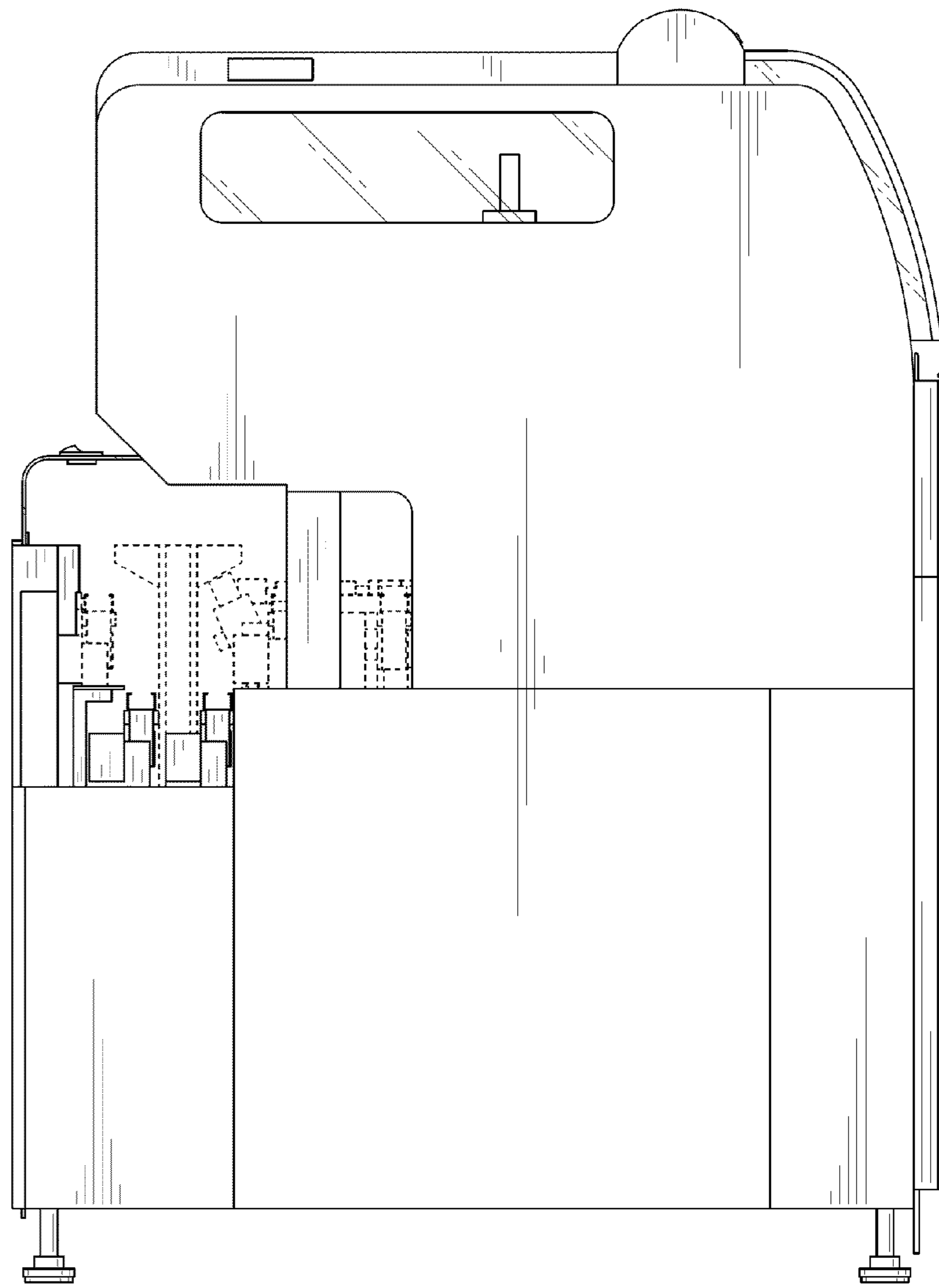


FIG. 4

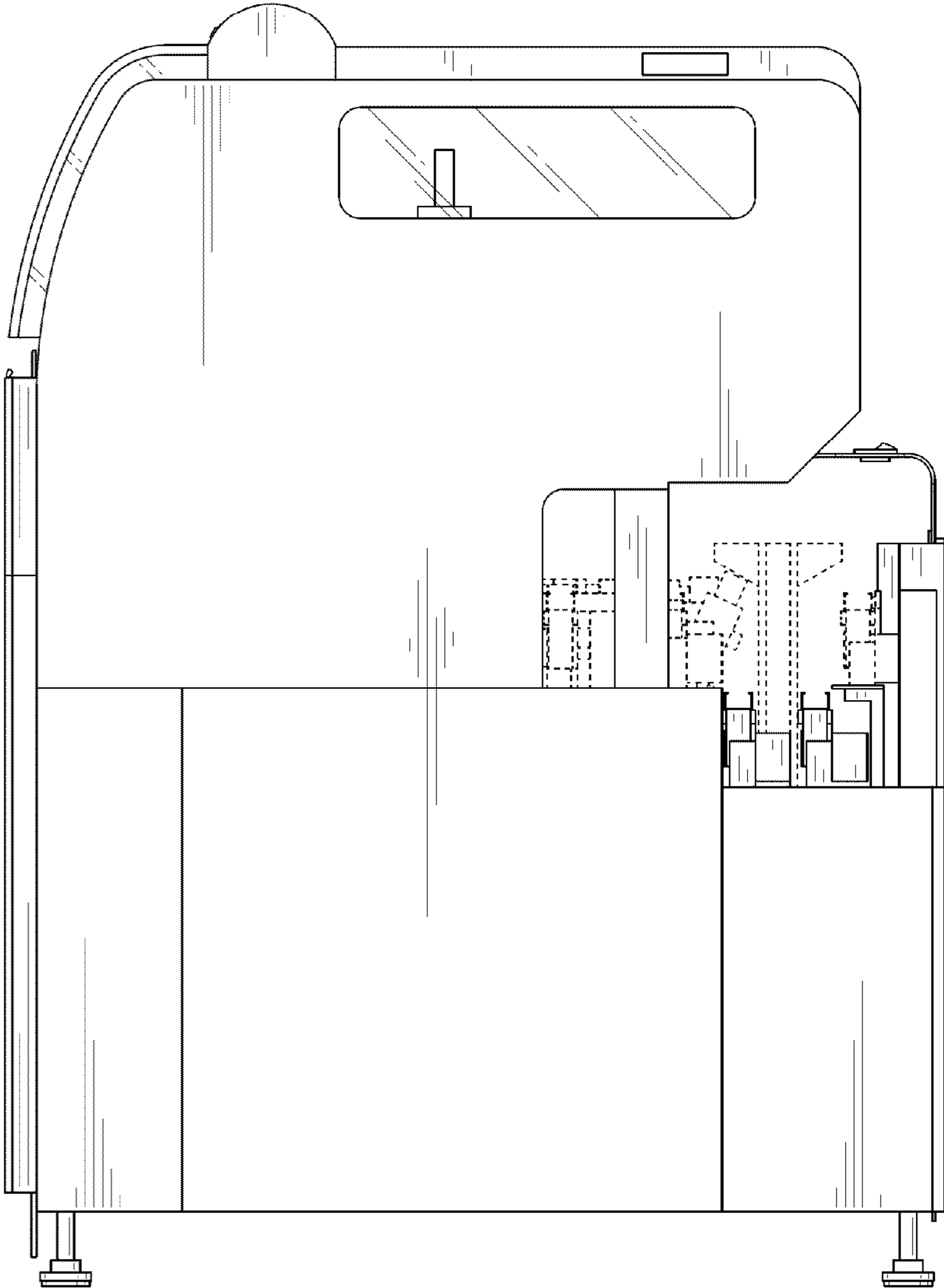


FIG. 5

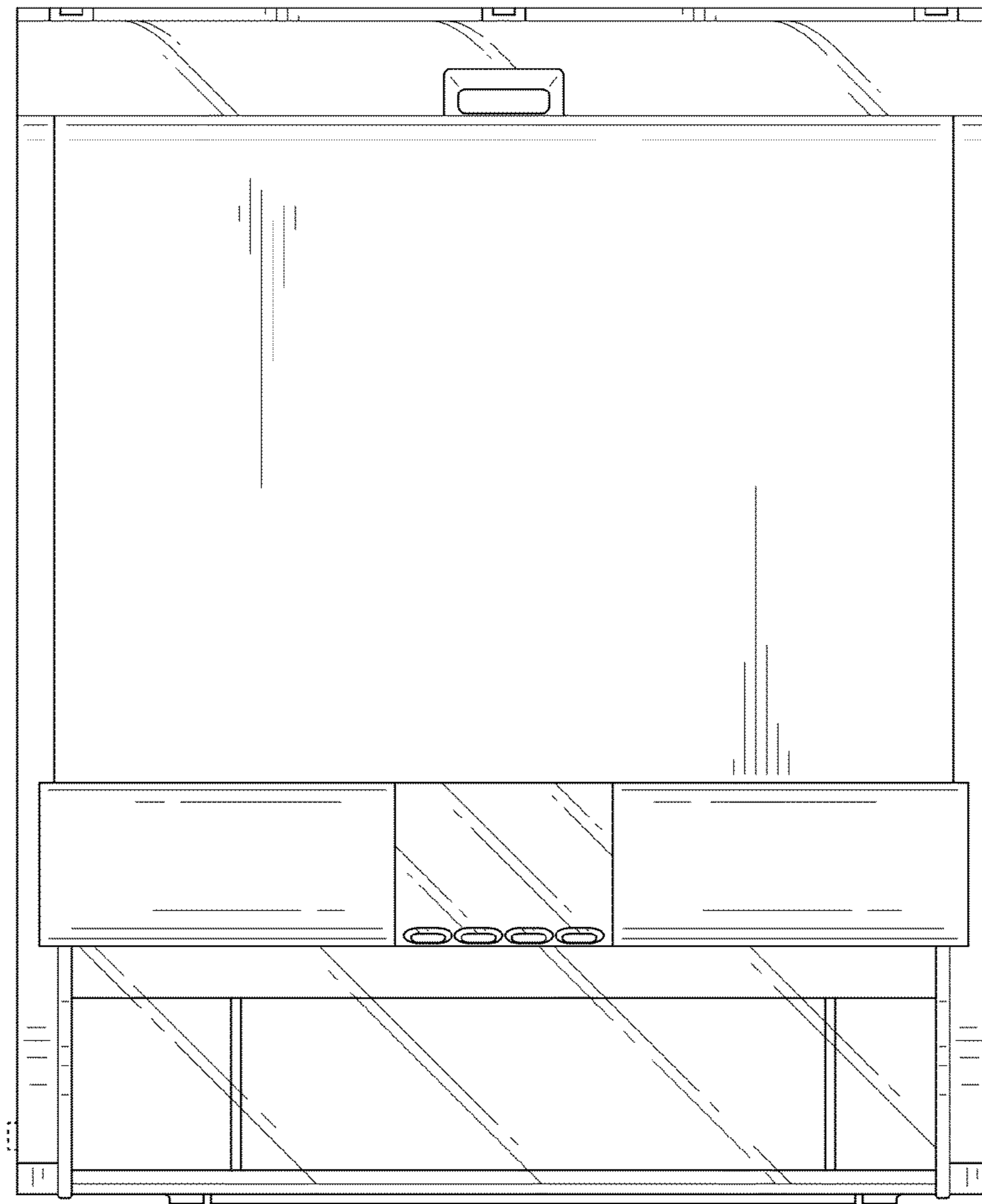


FIG. 6



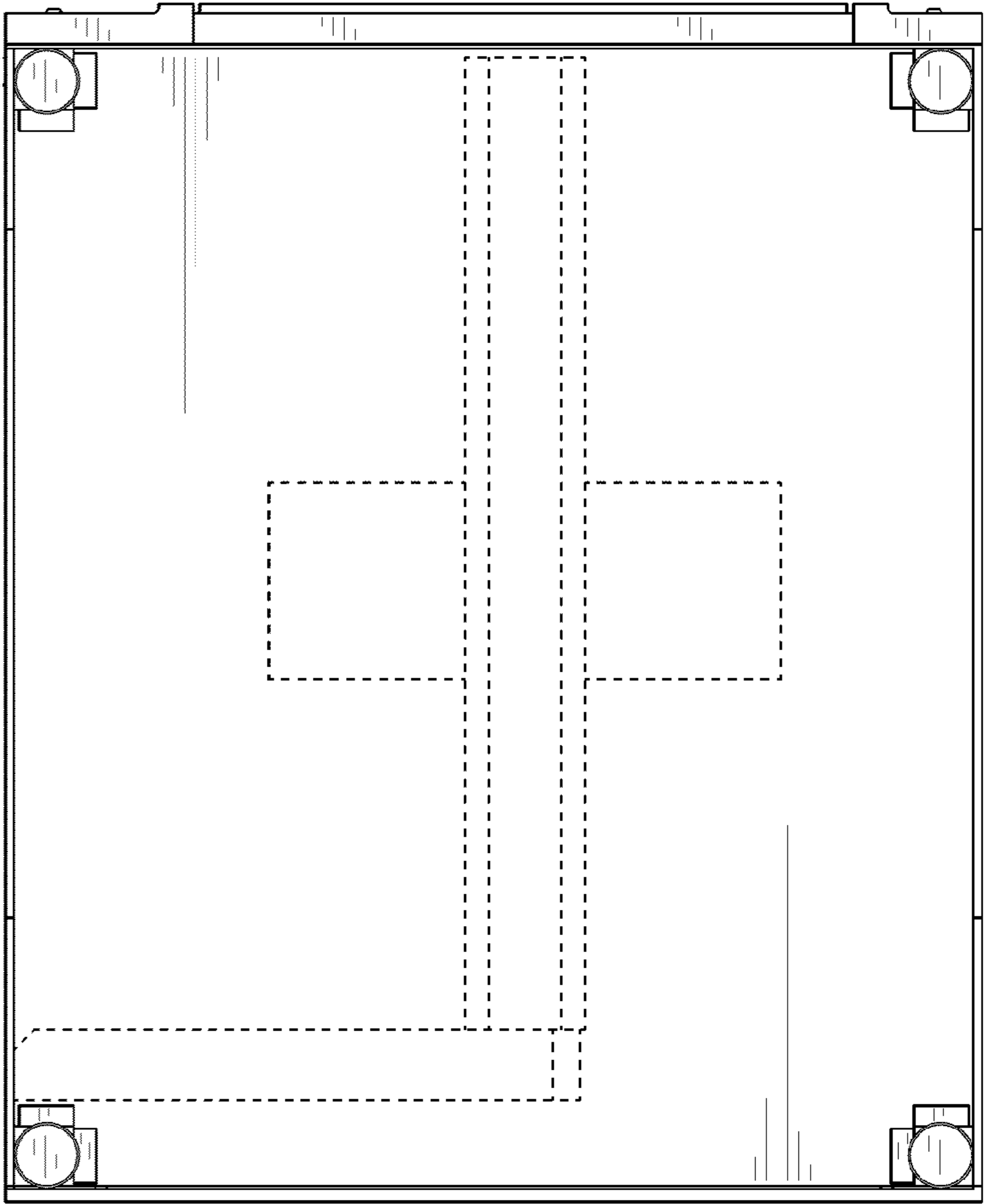


FIG. 7

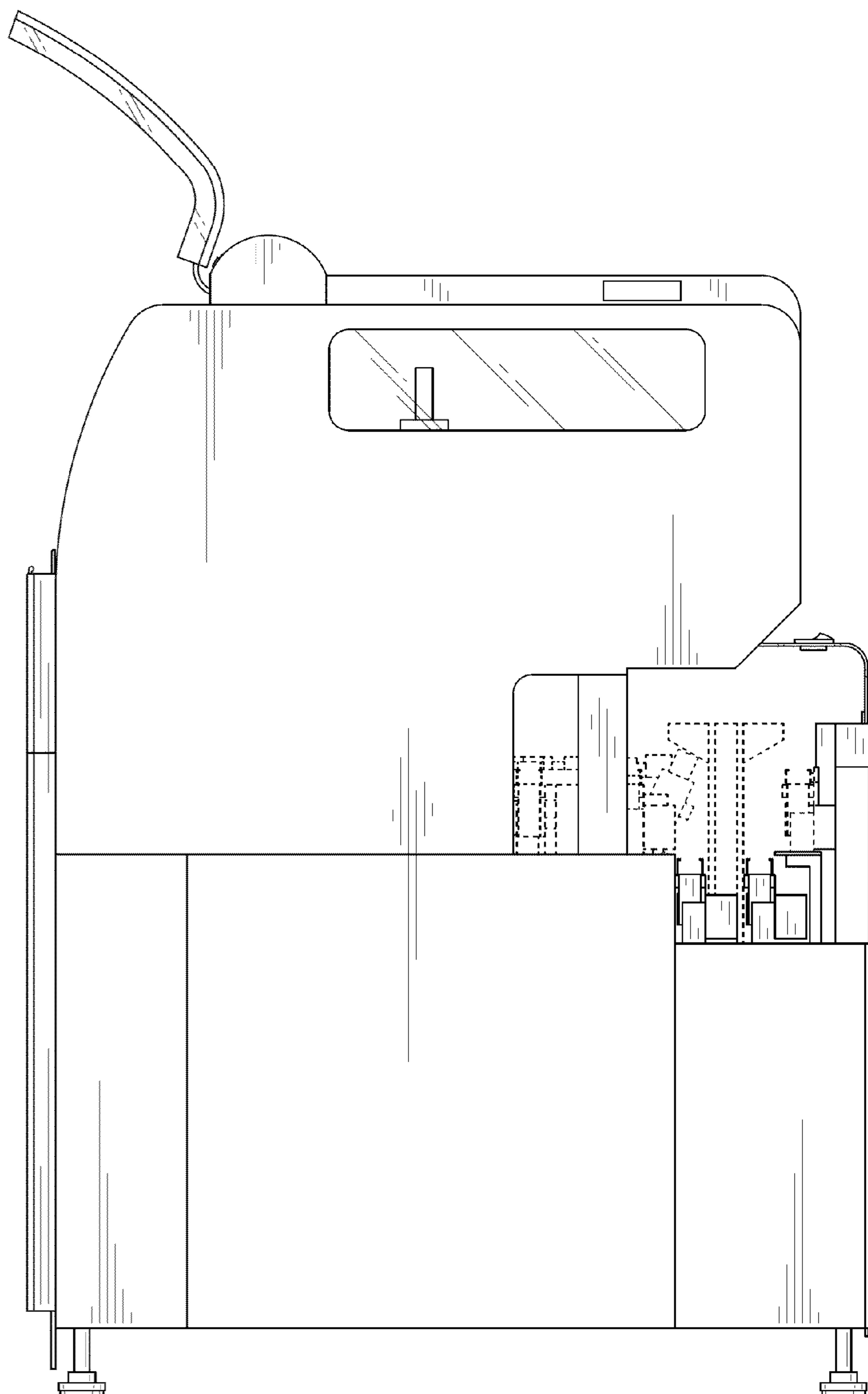


FIG. 8

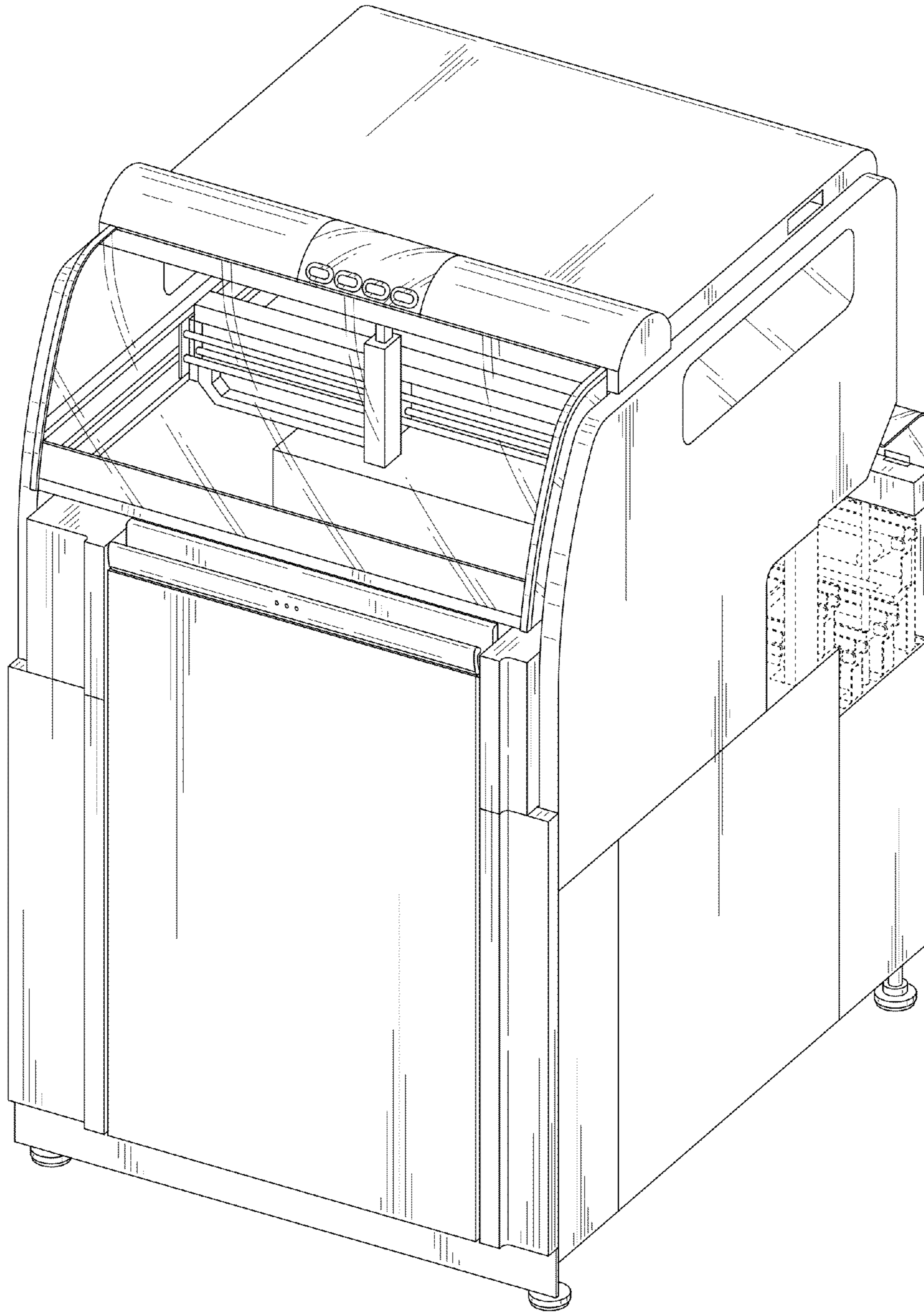


FIG. 9

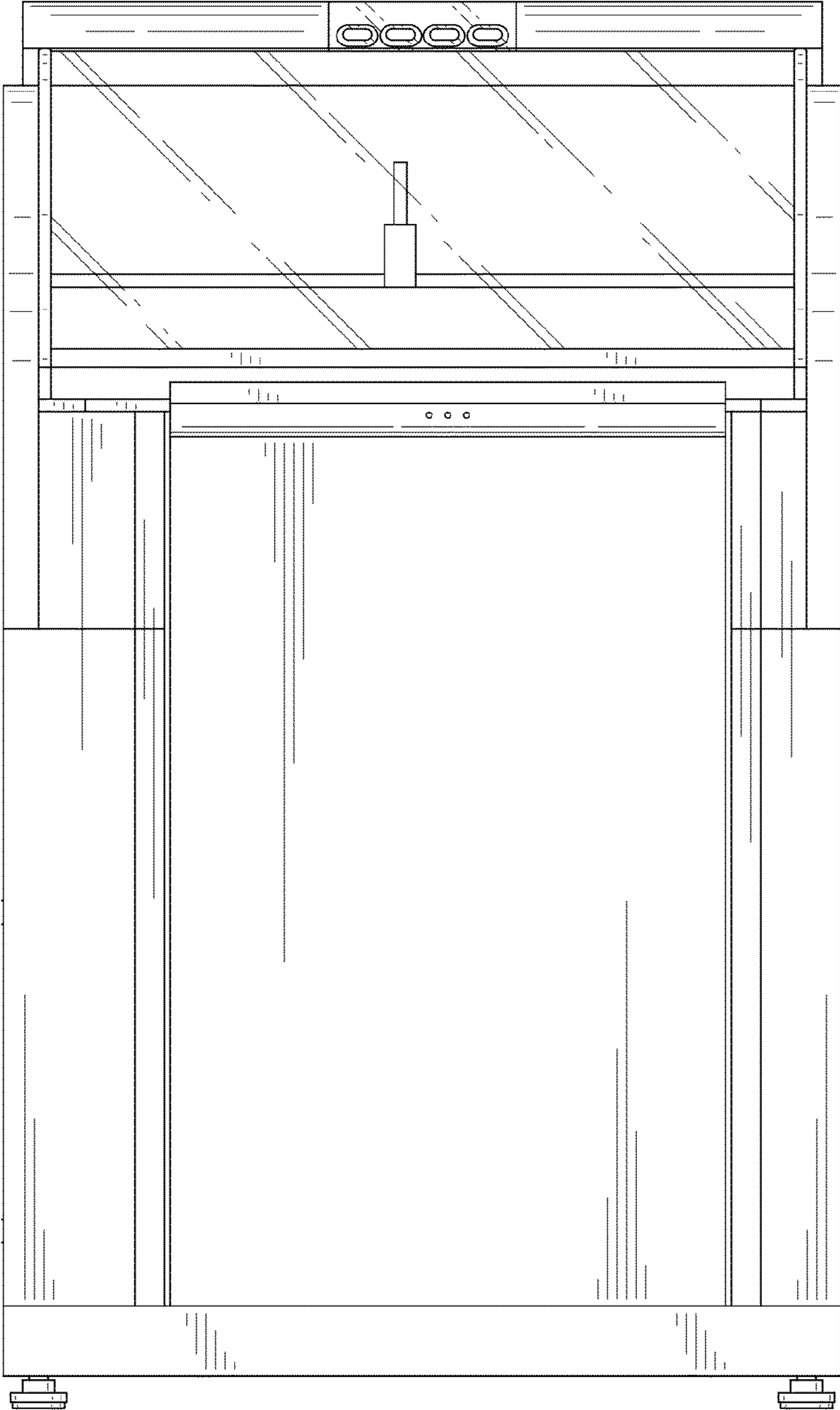


FIG. 10

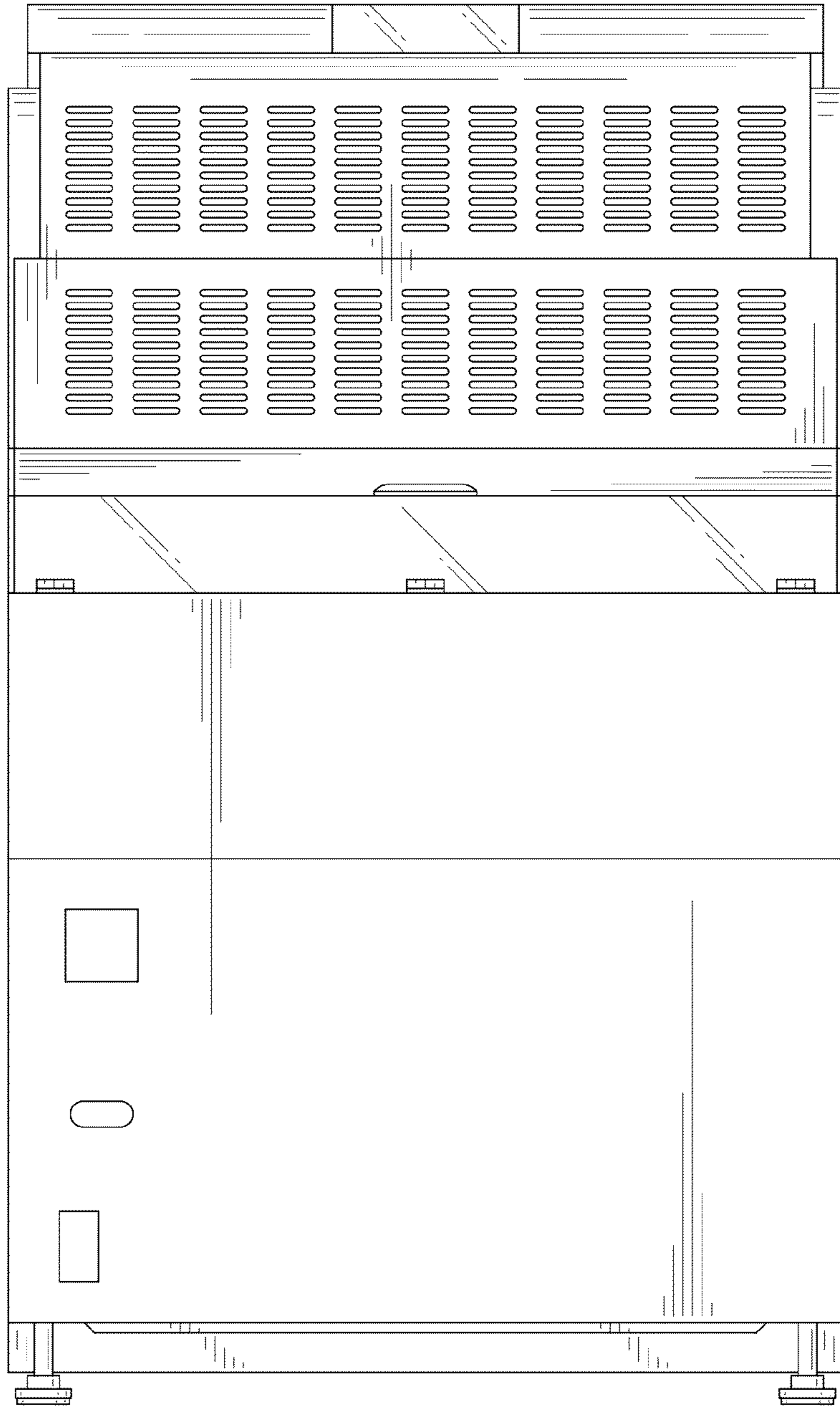


FIG. 11

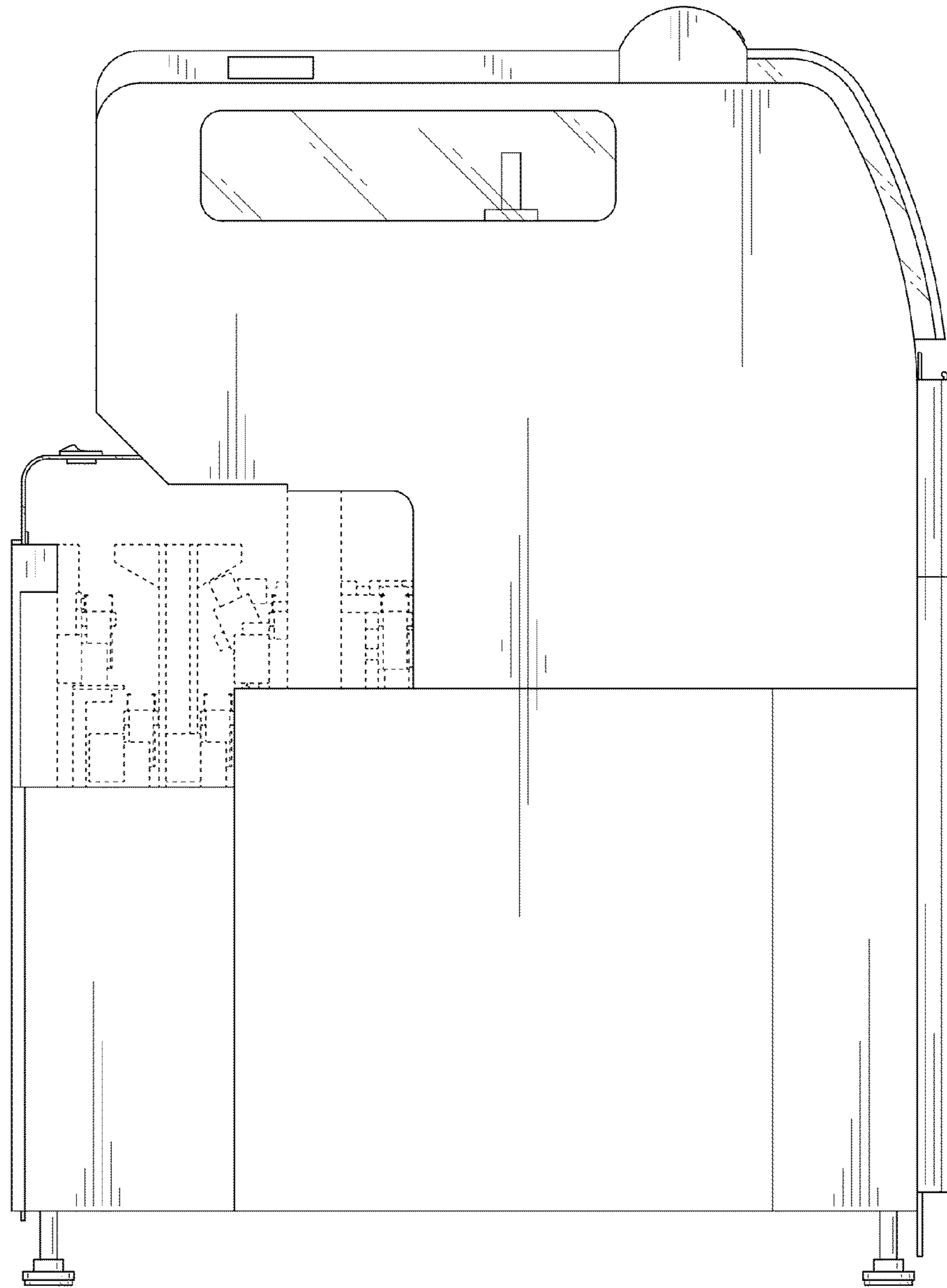


FIG. 12



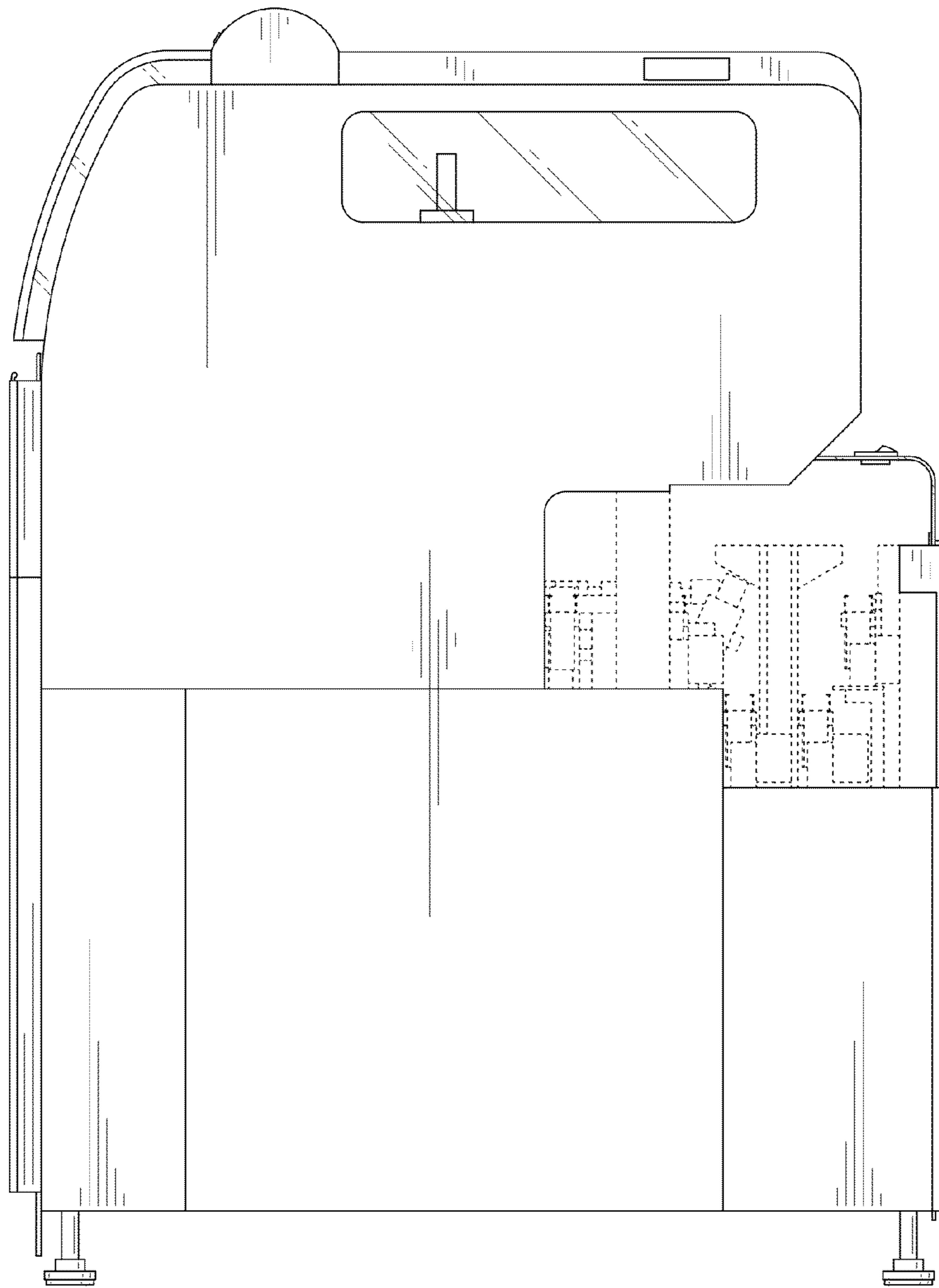
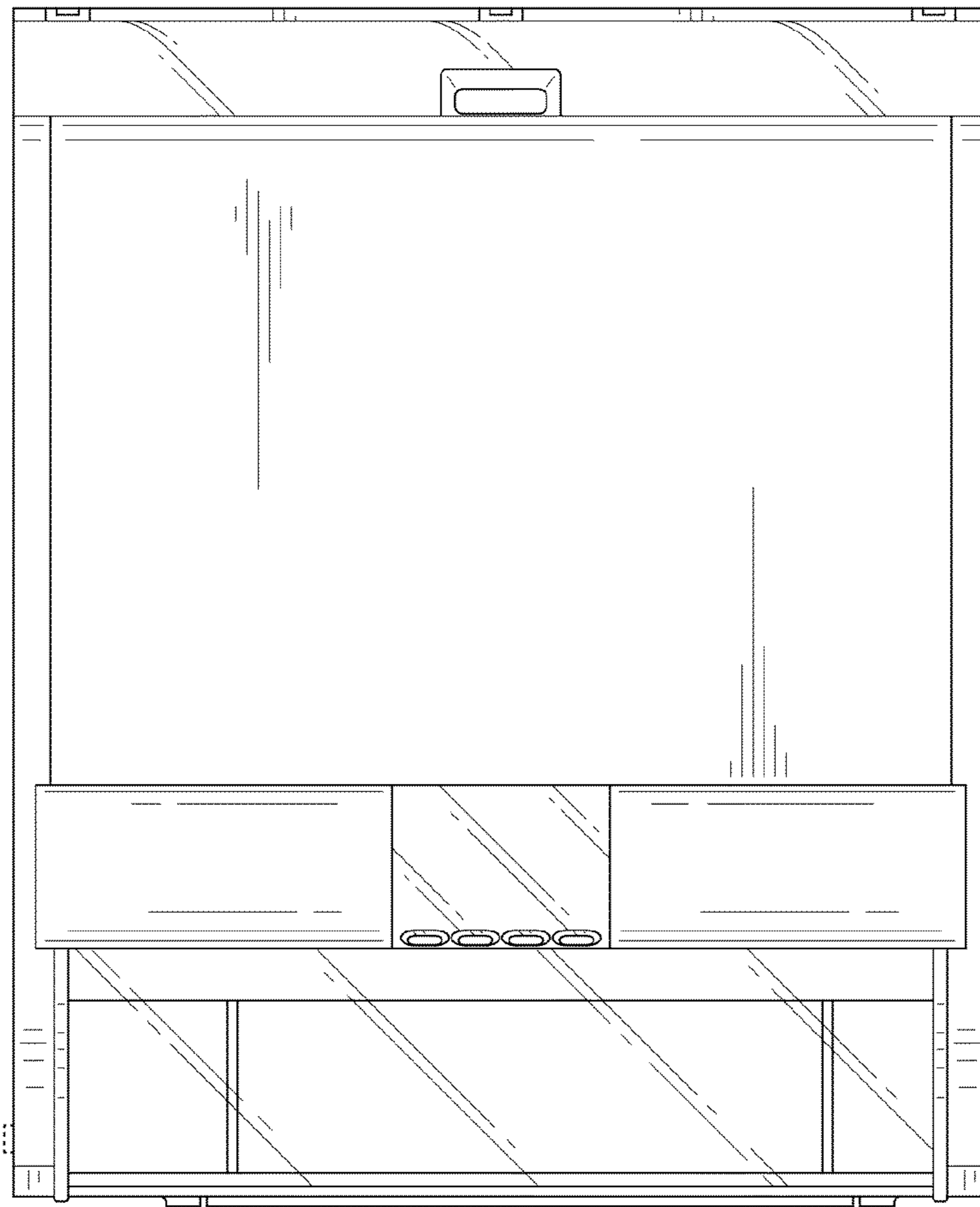


FIG. 13



*FIG. 14*

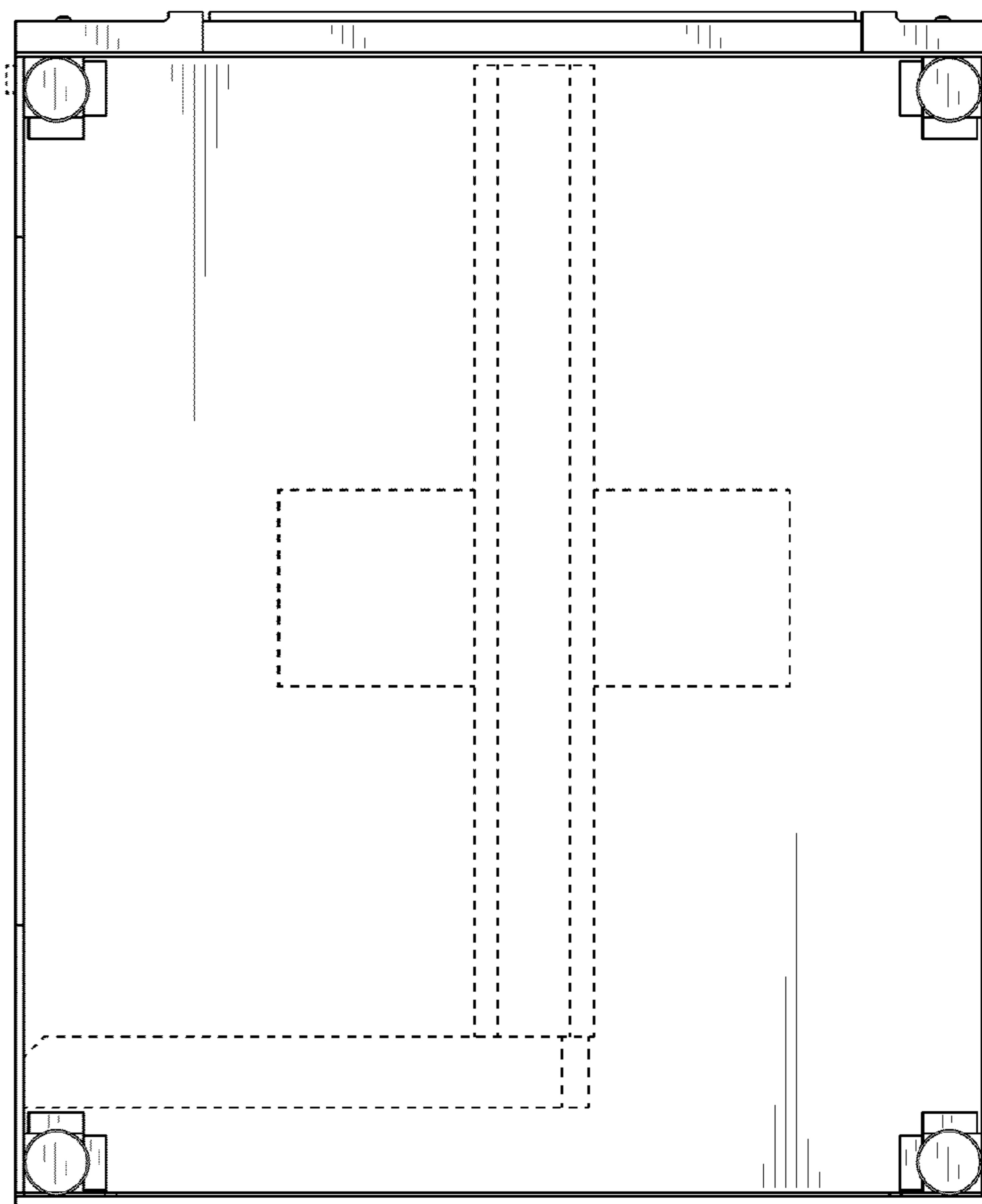


FIG. 15

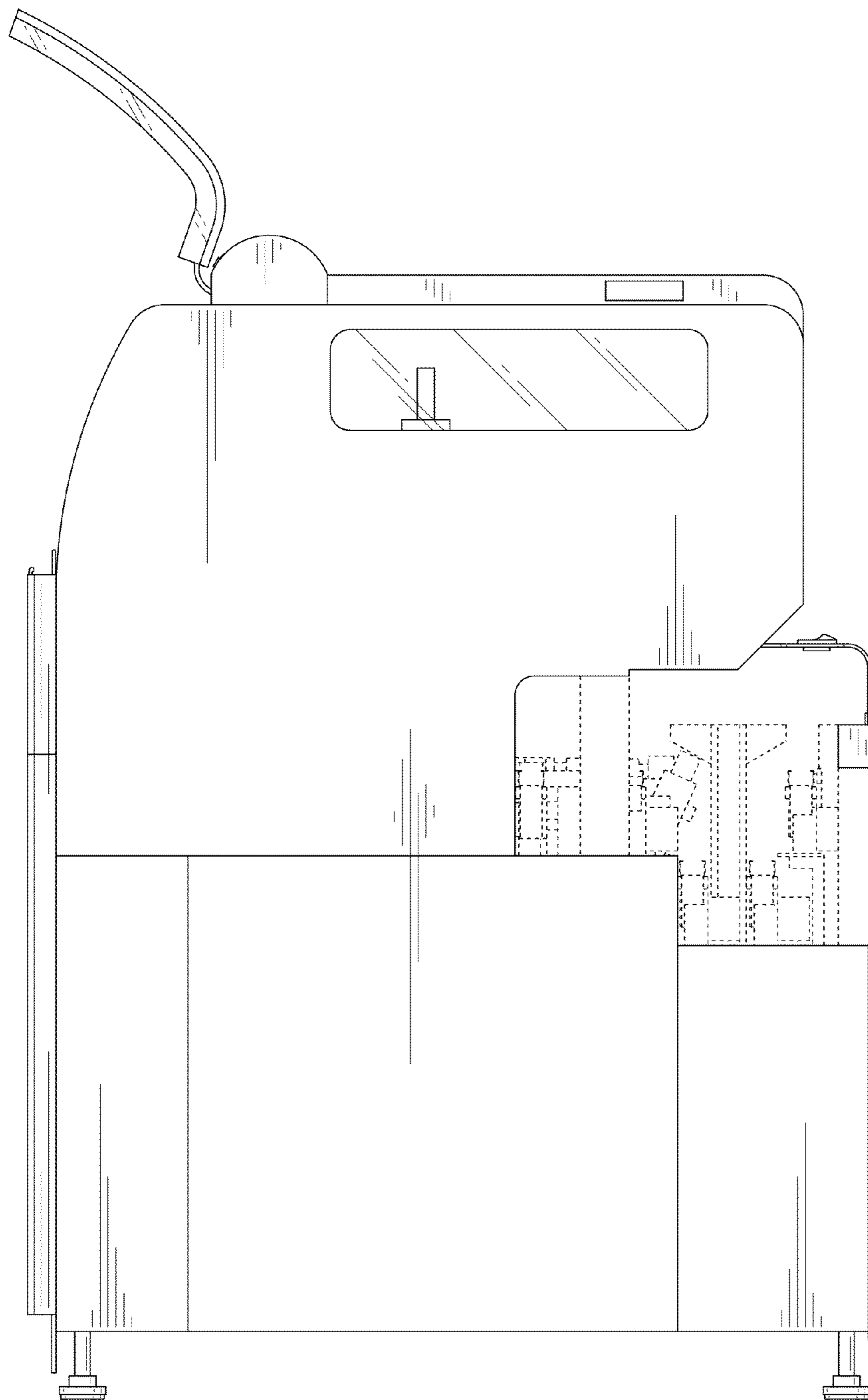


FIG. 16